

ABSTRACT

A semiconductor device comprising a semiconductor chip having a quadrangular main surface, a wiring substrate with the semiconductor chip disposed on a main surface thereof, a resin seal member for sealing the semiconductor chip, the resin seal member having a quadrangular main surface which confronts the main surface of the semiconductor chip, and a gate cut trace portion formed on a side face extending along a first side of the main surface of the resin seal member, wherein the first side of the main surface of the resin seal member extends along a first side of the main surface of the semiconductor chip, the main surface of the resin seal member has a second side intersecting the first side thereof, the second side of the main surface of the resin seal member extending along a second side of the main surface of the semiconductor chip which second side intersects the first side of the chip main surface, and in a section orthogonal to the second side of the main surface of the semiconductor chip, a sectional area of an area between the main surface of the wiring substrate and the main surface of the resin seal member at a position outside a side face of the semiconductor chip is smaller than a sectional area of an area between the main surface of the semiconductor chip and the main surface of the resin seal member. It is possible

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to suppress the occurrence of void.

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